

AMENDMENT TO THE CLAIMS

Claims 1-17. (Canceled)

Claim 18. (Currently Amended) A method for incorporating a thinned chip into a smart card, said chip having front and back sides, and being thinned from the back side, the method comprising the step steps of applying the thinned chip to a surface of the smart card with the chip front side directed outwardly from the smart card surface such that the surface of the smart card surface forming forms an external surface of the a finalized smart card, and then providing the card and chip with conductive paths.

Claim 19. (Canceled)

Claim 20. (Previously Presented) The method according to claim 18 or 19, including incorporating the chip into a cavity in the surface of the smart card.

Claim 21. (Previously Presented) The method according to claim 18, including pressing the chip into the surface of the smart card flush under the action of heat.

Claim 22. (Previously Presented) The method according to claim 18, including coating the chip located on the surface of the smart card with a protective lacquer.

Claims 23-26. (Canceled)

Claim 27. (Currently Amended) A smart card comprising a finalized smart card body having at least one thinned chip, said chip having front and back sides, and being thinned from the back side, the chip being disposed on a an external surface of

the smart card body with the chip front side directed outwardly from the smart card surface, said smart card body surface forming an external surface of the smart card wherein printed conductive paths are applied to the smart card and the chip on the outside thereof.

Claim 28. (Canceled)

Claim 29. (Canceled)

Claim 30. (Previously Presented) The smart card according to claim 27 or 28, wherein the chip is disposed in a cavity in the surface of the smart card.

Claim 31. (Previously Presented) The smart card according to claim 27, wherein the chip is pressed into the surface of the smart card flush.

Claim 32. (Previously Presented) The smart card according to claim 27, wherein the chip is coated with a protective lacquer.

Claim 33. (Currently Amended) A method for incorporating a thinned chip into a smart card having a finalized plastic card body, said chip having front back sides, and being thinned from the back side, the method comprising the steps of:

applying the chip to a card body an external surface of the card body with the chip front side facing outwardly from the card body surface, said card body surface forming an external surface of the smart card; and

providing the card body and chip with conductive paths;

wherein the chip is permanently secured by the card body.

Claim 34. (Canceled)

Claim 35. (Previously Presented) The method according to claim 33 or 34, further comprising the step of incorporating the chip into a cavity in the surface of the card body.

Claim 36. (Previously Presented) The method according to claim 33, further comprising the step of pressing the chip into the surface of the card body flush under the action of heat wherein the material of the card body surrounds the entirety of the chip with the exception of a front side of the chip facing outwardly from the surface of the card body.

Claim 37. (Previously Presented) The method according to claim 33, further comprising the step of coating the chip located on the surface of the card body with a protective lacquer.

Claim 38. (Previously Presented) The method according to claim 33, wherein the card body consists a single card body.

Claim 39. (Currently Amended) A smart card comprising a plastic card body having at least one thinned chip disposed on a card body an external surface of a finalized card body, said chip having front side and back sides, and being thinned from the back side, wherein the chip is permanently secured by the card body with the chip front side directed outwardly from the card body surface; wherein said card body surface forms an external surface of the smart cards; wherein conductive paths are applied to the card body and the chip on the outside thereof.

Claim 40. (Canceled)

Claim 41. (Canceled)

Claim 42. (Previously Presented) The smart card according to claim 39 or 40, wherein the chip is disposed in a cavity in the surface of the card body.

Claim 43. (Previously Presented) The smart card according to claim 39, wherein the chip is pressed into the surface of the card body flush.

Claim 44. (Previously Presented) The smart card according to claim 39, wherein the chip is coated with a protective lacquer.

Claim 45. (Previously Presented) The smart card according to claim 39, wherein the card body consists a single card body.

Claim 46. (Currently Amended) A method for incorporating a thinned chip into a smart card having a ~~finalized~~ plastic card body, comprising the steps of:

providing a plurality of contacts on an external surface of the card body;

placing the thinned a chip over at least portions of the plurality of contacts;

applying the chip to the external surface of the card body; and

permanently securing the chip to the card body;:

wherein the card body external surface forms an external surface of the smart card.

Claim 47. (Previously Presented) The method according to claim 46, further comprising the step of incorporating at least portions of the contacts into the card body.

Claim 48. (Previously Presented) The method according to claim 46, further comprising the step of incorporating the entirety of the contacts into the card body.

Claim 49. (New) The method of claim 18, wherein the step of providing the conductive paths includes printing the conductive paths.

Claim 50. (New) The method according to claim 18, wherein the step of applying the thinned chip to the surface of the smart card includes applying the thinned chip on an outermost surface of the smart card.

Claim 51. (New) The smart card according to claim 27, wherein the thinned chip is applied on an outermost surface of the smart card.